

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Isao OCHIAI

Group Art Unit: 1722

Serial No. 10/772,345

Examiner: Robert B. Davis

Filed: February 6, 2004

Attorney Docket No. 2905-107

Confirmation No.: 5051

For: **LEAD FRAME, RESIN SEALING MOLD AND METHOD FOR  
MANUFACTURING A SEMICONDUCTOR DEVICE USING THE SAME**

Customer Number: 66458

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE UNDER 37 C.F.R. 1.116**

Dear Sir:

In response to the final Office Action dated May 15, 2007, please amend the above-referenced application as follows:

**Amendments to the Claims** begin on page 2.

**Remarks** begin on page 5.

OK TO FILE  
9/12/07